LISTING OF THE CLAIMS:

Claim 1 (Currently Amended) A laminate support ~~used in the process of~~ for wire bonding a circuit device in large scale integrated circuitry, in which ~~is~~ said circuit device comprises a circuit pad arranged on a substrate, comprising:

said substrate being a closed woven mesh structure having a first surface supporting said circuit device; and

a wire ~~having a diameter~~ being positioned on said first surface of said substrate, said closed woven mesh structure of the substrate ~~including a closed woven mesh~~ having a thickness of between about 2.5 and 4.0 mils and being constituted of fiberglass having strands ~~whose~~ possessing separation ~~distance is~~ distances which are equal to or less than ~~said diameter~~ a cross-sectional diameter of said wire positioned on said first surface of said substrate, said separation ~~distance~~ distances between said strands being within the range of about 0.2 to 0.7 mils so as to ~~substantially~~ prevent deformation and collapse of said circuit device ~~during said process of~~ in response to wire bonding.

Claims 2-5 (Cancelled).

Claim 6 (Currently Amended) The laminate support ~~used in the process of wire bonding a circuit device~~ in accordance with claim 1, wherein said circuit device ~~is a~~ comprises said circuit pad of large scale integrated design.

Claim 7 (Currently Amended) ~~A~~ The laminate support ~~used in the process of wire bonding a circuit device which is arranged on a substrate, comprising:~~ in accordance with claim 1, wherein:

~~said substrate having a first surface supporting said circuit device; and~~

~~a wire having a thickness positioned on said first surface of said substrate,~~ said closed woven mesh structure of said substrate ~~including a closed woven mesh having a thickness of between about 2.5 to 4.0 mils and being~~ is constituted of fiberglass having warp and weave strands, whose separation ~~distance is~~ distances are equal to or less than the thickness of said wire on said first surface of said substrate, as measured lengthwise through said closed woven mesh~~, said separation distance of said strands being within the range of about 0.2 to 0.7 mils so as to substantially prevent deformation and collapse of said circuit device during said process of wire bonding~~.

Claims 8-11 (Cancelled).

Claim 12 (Cancelled).